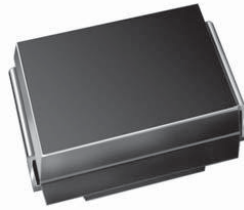


## Surface Mount Ultrafast Rectifier


**DO-214AA (SMB)**

### FEATURES

- Low profile package
- Ideal for automated placement
- Oxide planar chip junction
- Ultrafast recovery times for high frequency
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified
- Material categorization: For definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)


**RoHS**  
COMPLIANT

### TYPICAL APPLICATIONS

For use in secondary rectification and freewheeling for ultrafast switching speeds of AC/AC and DC/DC converters in high temperature conditions for both consumer and automotive applications.

### PRIMARY CHARACTERISTICS

$I_{F(AV)}$	2.0 A
$V_{RRM}$	100 V, 150 V, 200 V
$I_{FSM}$	50 A
$t_{rr}$	25 ns
$V_F$ at $I_F = 2.0$ A	0.69 V
$T_J$ max.	175 °C

### MECHANICAL DATA

**Case:** DO-214AA (SMB)

Molding compound meets UL 94 V-0 flammability rating

Base P/N-E3 - RoHS compliant, commercial grade

Base P/NHE3 - RoHS compliant, AEC-Q101 qualified

**Terminals:** Matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

E3 suffix meets JESD 201 class 1A whisker test, HE3 suffix meets JESD 201 class 2 whisker test

**Polarity:** Color band denotes cathode end

### MAXIMUM RATINGS ( $T_A = 25$ °C unless otherwise noted)

PARAMETER	SYMBOL	UH2B	UH2C	UH2D	UNIT
Device marking code		HB	HC	HD	
Maximum repetitive peak reverse voltage	$V_{RRM}$	100	150	200	V
Maximum average forward rectified current (fig. 1) <sup>(1)</sup>	$I_{F(AV)}$	2.0			A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	$I_{FSM}$	50			A
Operating junction and storage temperature range	$T_J, T_{STG}$	- 55 to + 175			°C

#### Note

<sup>(1)</sup> Free air, mounted on recommended copper pad area



ELECTRICAL CHARACTERISTICS (T <sub>A</sub> = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	I <sub>F</sub> = 1.0 A	T <sub>A</sub> = 25 °C	V <sub>F</sub> <sup>(1)</sup>	0.79	-	V
	I <sub>F</sub> = 2.0 A			0.87	1.05	
	I <sub>F</sub> = 1.0 A	T <sub>A</sub> = 125 °C		0.62	-	
	I <sub>F</sub> = 2.0 A			0.69	0.90	
Reverse current	Rated V <sub>R</sub>	T <sub>A</sub> = 25 °C	I <sub>R</sub> <sup>(2)</sup>	-	2.0	μA
		T <sub>A</sub> = 125 °C		10	50	
Maximum reverse recovery time	I <sub>F</sub> = 0.5 A, I <sub>R</sub> = 1.0 A, I <sub>rr</sub> = 0.25 A	T <sub>A</sub> = 25 °C	t <sub>rr</sub>	15	25	ns
Typical reverse recovery time	I <sub>F</sub> = 1.0 A, dI/dt = 50 A/μs, V <sub>R</sub> = 30 V, I <sub>rr</sub> = 0.1 I <sub>RM</sub>			20	35	
Typical softness factor (t <sub>b</sub> /t <sub>a</sub> )	I <sub>F</sub> = 2.0 A, dI/dt = 200 A/μs, V <sub>R</sub> = 200 V	T <sub>A</sub> = 125 °C	S	0.3	-	
Typical reverse recovery current			I <sub>RM</sub>	5.0	6.0	A
Typical stored charge			Q <sub>rr</sub>	55	-	nC
Typical junction capacitance			C <sub>J</sub>	42	-	pF

**Notes**

(1) Pulse test: 300 μs pulse width, 1 % duty cycle

(2) Pulse test: Pulse width ≤ 40 ms

THERMAL CHARACTERISTICS (T <sub>A</sub> = 25 °C unless otherwise noted)					
PARAMETER	SYMBOL	UH2B	UH2C	UH2D	UNIT
Typical thermal resistance	R <sub>θJA</sub> <sup>(1)</sup>	105			°C/W
	R <sub>θJM</sub> <sup>(1)</sup>	15			

**Note**(1) Free air, mounted on recommended copper pad area. Thermal resistance R<sub>θJA</sub> - junction to ambient, R<sub>θJM</sub> - junction to mount

ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
UH2D-E3/52T	0.100	52T	750	7" diameter plastic tape and reel
UH2D-E3/5BT	0.100	5BT	3200	13" diameter plastic tape and reel
UH2DHE3/52T <sup>(1)</sup>	0.100	52T	750	7" diameter plastic tape and reel
UH2DHE3/5BT <sup>(1)</sup>	0.100	5BT	3200	13" diameter plastic tape and reel

**Note**

(1) AEC-Q 101 qualified



RATINGS AND CHARACTERISTICS CURVES

(T<sub>A</sub> = 25 °C unless otherwise noted)

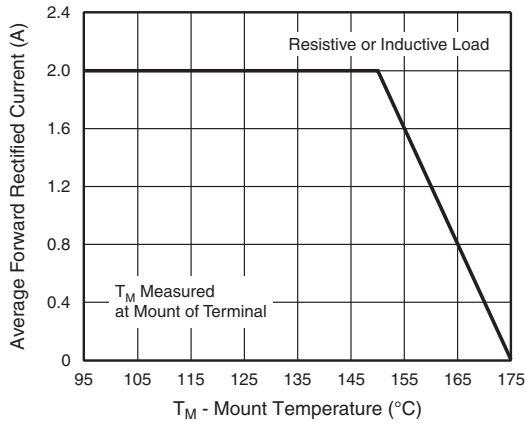


Fig. 1 - Maximum Forward Current Derating Curve

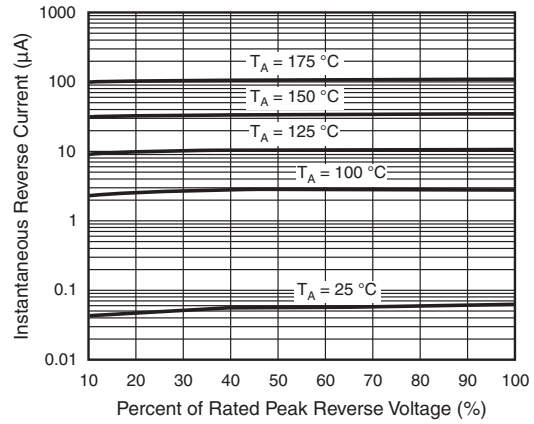


Fig. 4 - Typical Reverse Characteristics

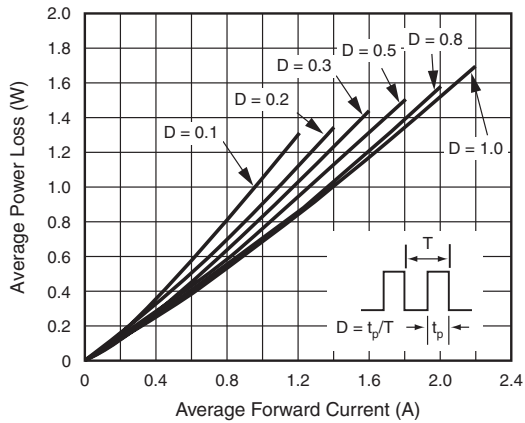


Fig. 2 - Forward Power Loss Characteristics

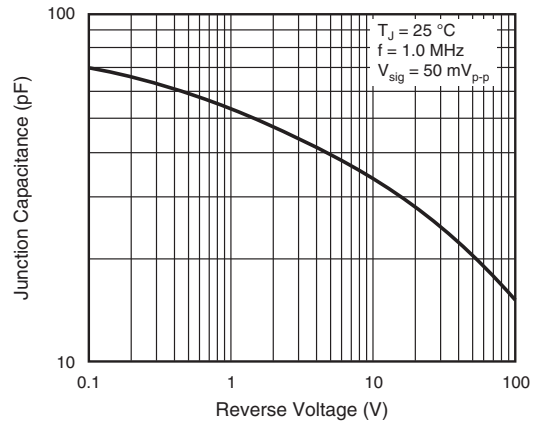


Fig. 5 - Typical Junction Capacitance

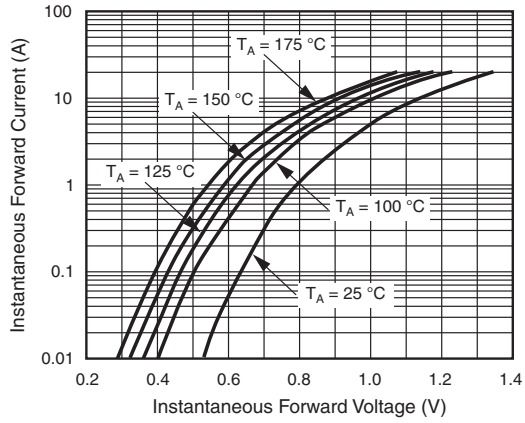


Fig. 3 - Typical Instantaneous Forward Characteristics

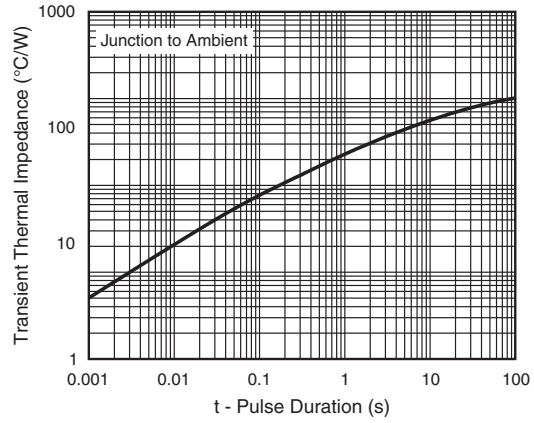
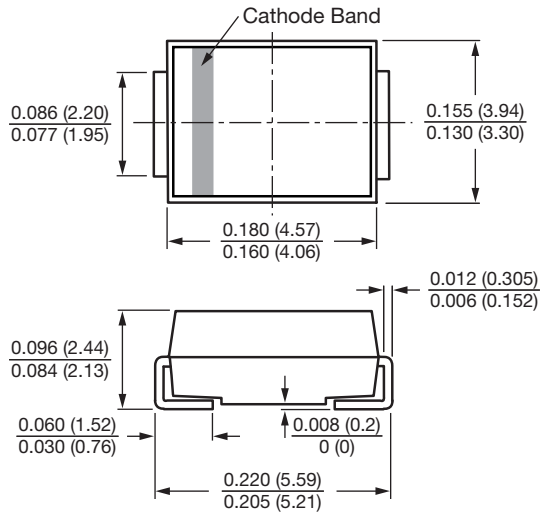


Fig. 6 - Typical Transient Thermal Impedance

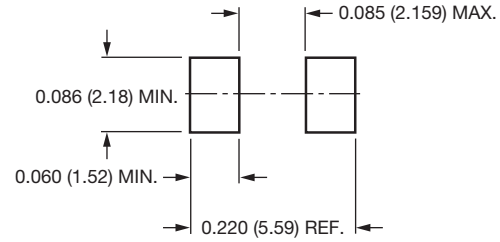


### PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

DO-214AA (SMB)



Mounting Pad Layout





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